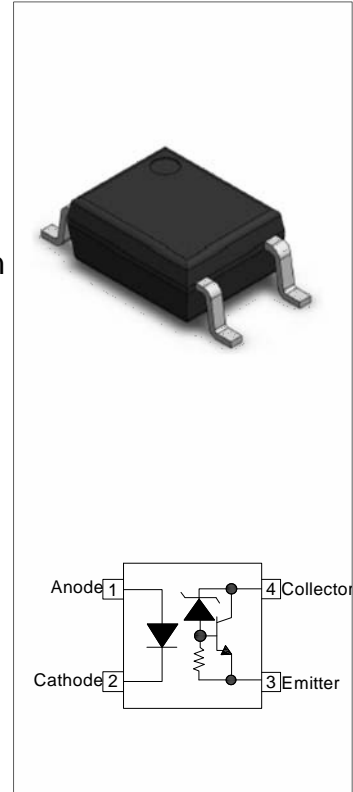


### DESCRIPTION:

The products are transistor output opto-couplers in a plastic SOP4 package. The device which is infrared LED chip and Photo-transistor chip are assembled on lead frame, in order to change the electricity-light-electricity. The products are widely used in transmission and conversion of digital logic, power control and switch, electric insulation and impedance conversion between circuits systems.



### MAIN FEATURES

- High isolation 3750 VRMS
- Operating temperature range -55°C to 110°C
- RoHS & REACH Compliance
- HBM: H3A; MM: M4; CDM:C3
- CQC approved
- VDE approved
- UL approved

### ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	$I_F$	50	mA
	Peak Forward Current	$I_{FP}$	1	A
	Reverse Voltage	$V_R$	6	V
	Power Dissipation	$P_D$	75	mW
Output	Collector-emitter Voltage	$V_{CEO}$	40	V
	Emitter-collector Voltage	$V_{ECO}$	7	V
	Collector Current	$I_C$	50	mA
	Power Dissipation	$P_C$	150	mW
Total Power Dissipation		$P_{tot}$	225	mW
Isolation Voltage		$V_{iso}$	3750	Vrms
Operating Temperature		$T_{opr}$	-55~+110	
Junction Temperature		$T_j$	125	

Storage Temperature	T <sub>stg</sub>	-55~+125	
Soldering Temperature	T <sub>sol</sub>	260	

NOTE1: 100 $\mu$ s pulse, 100Hz frequency

NOTE2 AC for 1minute, R.H.=40~60%

**ELECTRICAL CHARACTERISTICS** (Temperature=25°C)

Parameter	Symbol	Condition	Min.	Typ 1
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ORDERING INFORMATION

<p><b>J</b></p> <p>JieJie Microelectronics Co., Ltd.</p>	<p><b>OC</b></p> <p>Opto Coupler</p>	<p><b>T</b></p> <p>Transistor</p>	<p><b>357</b></p> <p>Marketization Model</p>	<p><b>B</b></p> <p>CTR Rank:D/None</p>	<p><b>k</b></p> <p>k: Medium-speed</p>	<p><b>-M4</b></p> <p>SOP4</p>	<p><b>/</b></p> <p>None:T1 R:T2</p>
--	--------------------------------------	-----------------------------------	--	--	--	-------------------------------	---

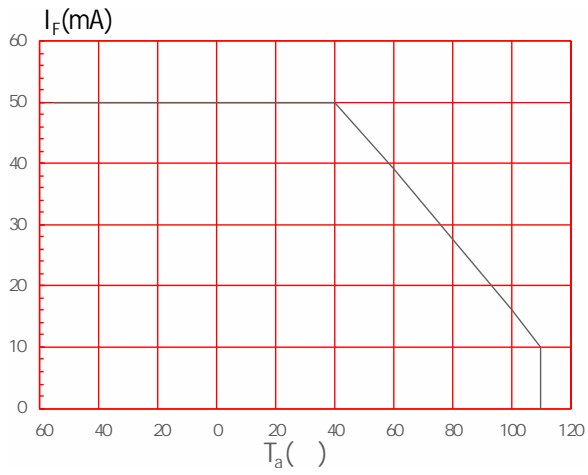
Packing Quantity	
Option	Quantity
None/R	3000 Units/Reel

MARKING

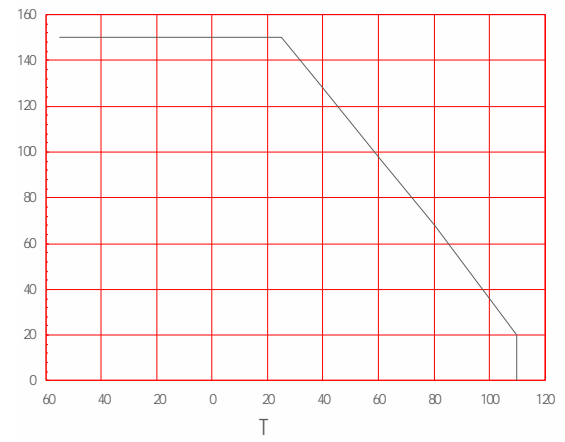


Characteristics Curves

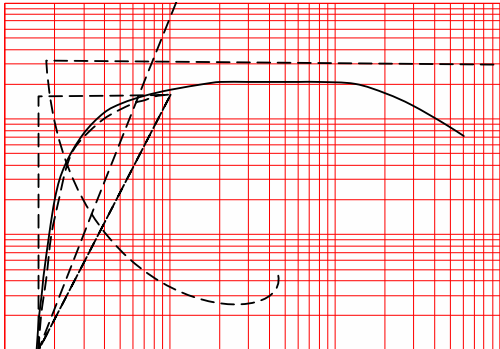
**FIG.1:** Max. Allowable LED Forward Current vs. Ambient Temperature



**FIG.2:** Collector Power Dissipation vs. Ambient Temperature



**FIG.7:** Current Transfer Ratio vs. Forward Current

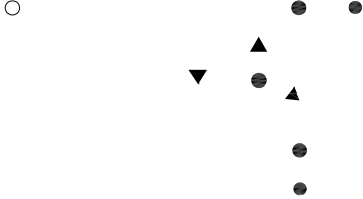


**FIG.8:** Normalized Collector-emitter Saturation Voltage vs. Ambient Temperature

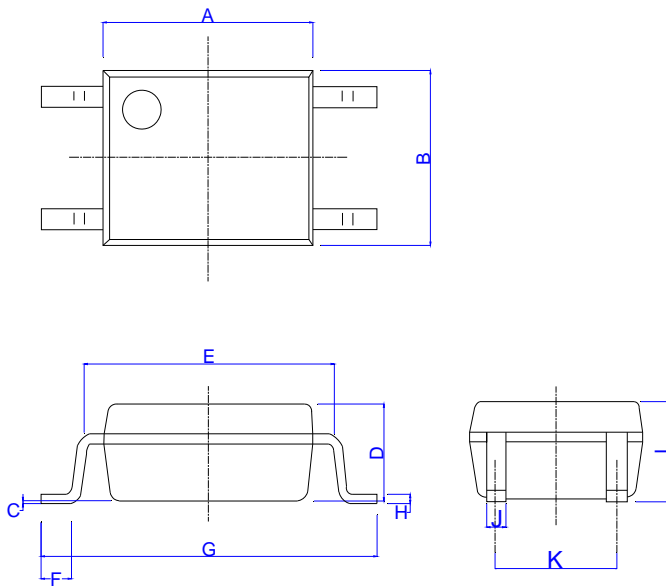
Test Circuits

FIG.13: Test Circuits of Propagation Delay Time

FIG.14: Curves of Propagation Delay Time

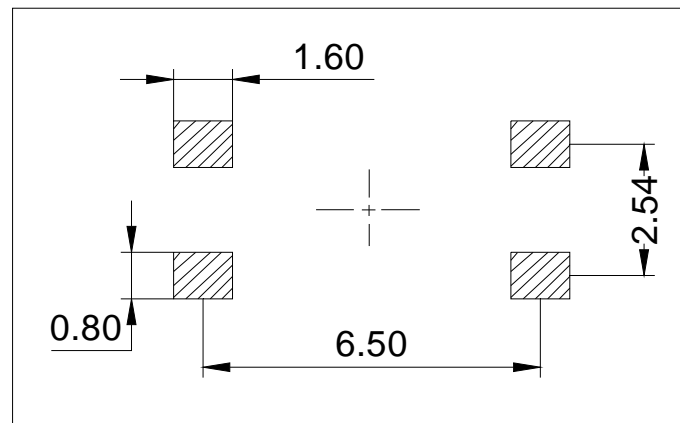


Package Dimension (Unit: mm)



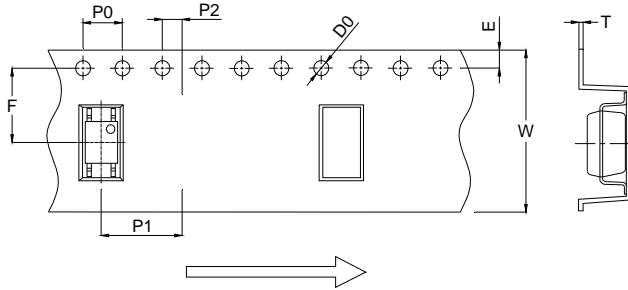
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.80	0.173		0.189
B	3.60		4.20	0.142		0.165
C	0.00		0.20	0.000		0.008
D	1.90		2.30	0.075		0.091
E	5.00		5.60	0.197		0.220
F	0.34		0.94	0.013		0.037
G	6.70		7.30	0.264		0.287
H	0.10		0.30	0.004		0.012
I	2.00		2.40	0.079		0.094
J	0.25		0.55	0.010		0.022
K	2.29		2.79	0.090		0.110

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



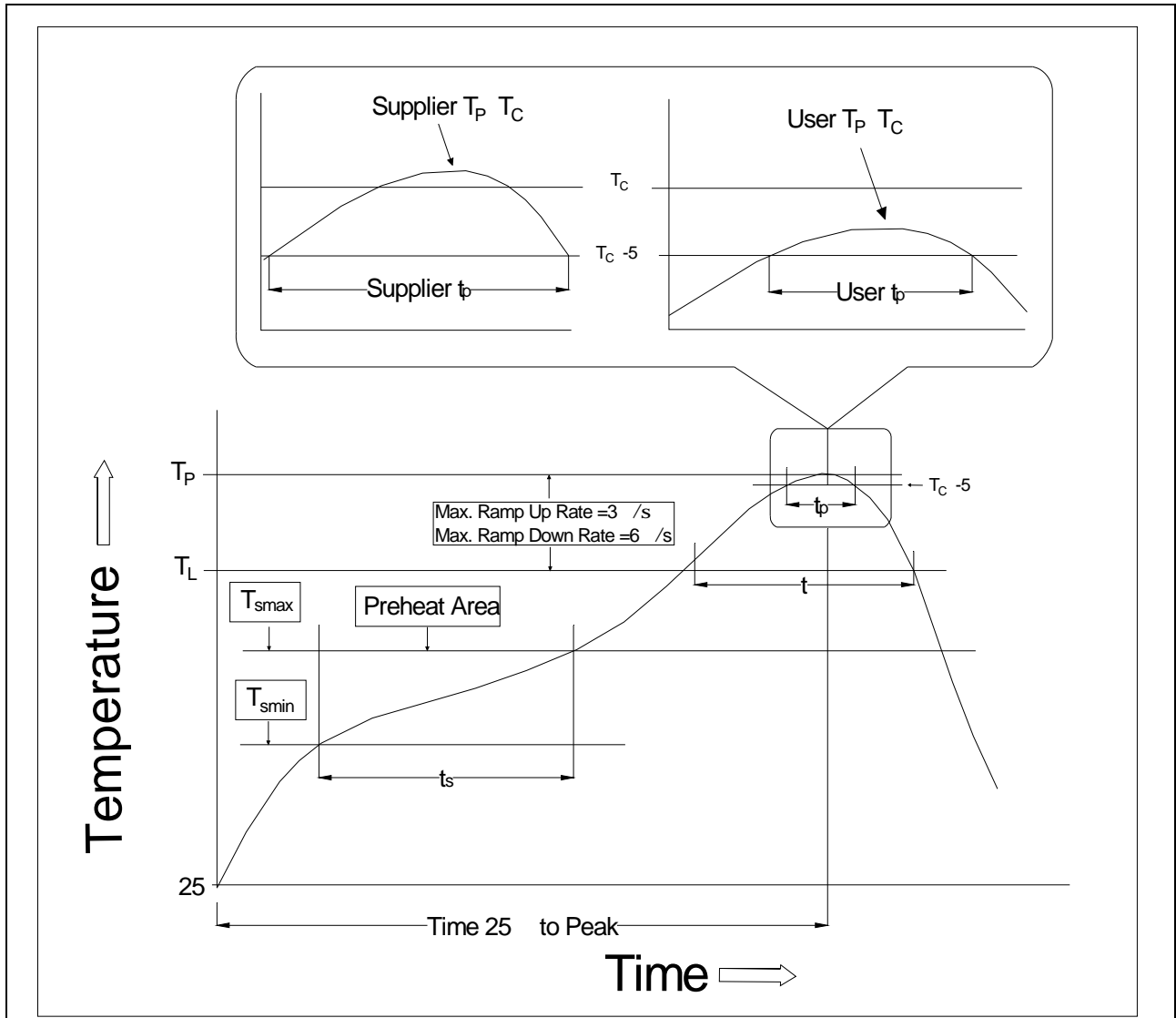
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option None



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0						
P0						
P1						
P2						
E						
F						
T						
W						

REFLOW INFORMATION




Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	100	150
Temperature Max. (T <sub>smax</sub> )	150	200
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds	60-120 seconds
Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3 °/second max.	3 °/second max.
Liquidus Temperature (T <sub>L</sub> )	183	217
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;  
Recommend storage humidity: <60%;  
MSL level: MSL 1

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